

IN THE CLAIMS

1. (Previously presented) An apparatus for manufacturing semiconductor devices, comprising:
 - a susceptor on which a substrate is positioned;
 - a lift pin assembly for loading the substrate onto the susceptor;
 - a plurality of guiding blocks disposed around an edge of the susceptor, for positioning the substrate at an aligned position on the susceptor; and
 - a guiding block transfer unit for collectively moving the guiding blocks radially on the susceptor, the guiding block transfer unit comprising a plurality of transfer rods, with each transfer rod coupled to a respective one of the guiding blocks by an attachment assembly extending through elongate openings formed in the guiding block and transfer rod, the attachment assembly being movable within the opening in the transfer rod to facilitate movement of the guiding block to a plurality of predetermined positions.
2. (Original) The apparatus of claim 1, wherein the susceptor comprises:
 - a plate; and
 - a spacer disposed at the edge of the plate on which the edge of the substrate is laid, said spacer including a guiding lane along which the guiding blocks are moved.
3. (Previously presented) The apparatus of claim 2, wherein each of the guiding blocks moves along the guiding lane within a range defined by a radius of the plate.
4. (Previously presented) The apparatus of claim 3, wherein the guiding block transfer unit comprises:
 - a shaft rotatable by a driver in a predetermined range of distances; and
 - a plurality of horizontally-extending supporting rods attached to the shaft,wherein the plurality of transfer rods are connected between the supporting rods and the guiding blocks, the transfer rods being pivotally coupled to the supporting rods so that when the shaft rotates, the guiding blocks move along the guiding lanes and the transfer rods pivot.

5. (Previously presented) The apparatus of claim 4, wherein each of the transfer rods comprise:

- a horizontal portion pivotally coupled to the supporting rods;
- a vertical portion coupled to the horizontal portion; and
- a connection portion pivotally coupled to the vertical portion and the guiding block.

6. (Original) The apparatus of claim 1, wherein the guiding blocks are movable to a plurality of positions based on processing temperature.

7. (Cancelled)

8. (Original) The apparatus of claim 5, further comprising a resilient element connected between the transfer rod and the plate, the resilient element being capable of moving the guiding block to a predetermined position.

9. (Original) The apparatus of claim 3, further comprising a testing unit for determining the location of the substrate on the susceptor.

10. (Original) The apparatus of claim 9, wherein the testing unit comprises:
a vacuum line in communication with a vacuum pump which extends to the upper space of the plate; and
a sensor for detecting pressure in the vacuum line.

11. (Previously presented) The apparatus of claim 1, which is employed in a baking process conducted during fabricating of said semiconductor devices.

12-17. (Cancelled)

18. (Currently amended) A method for manufacturing a semiconductor devices, the method comprising:

- providing a susceptor on which a semiconductor substrate is positioned;

loading the substrate onto the susceptor;
providing a plurality of guiding blocks disposed around the edge of the susceptor;
positioning the substrate at a predetermined, aligned position on the susceptor;
moving the guiding blocks on the susceptor; and
providing a guiding block transfer unit for collectively and radially moving the guiding blocks on the susceptor, the guiding block transfer unit comprising a plurality of transfer rods, with each transfer rod coupled to a respective one of the guiding blocks by an attachment assembly extending through elongate openings formed in the guiding block and transfer rod, the attachment assembly being movable within the opening in the transfer rod to facilitate movement of the respective one of the guiding blocks to a plurality of predetermined positions.

19. (Original) The method of claim 18, which further comprises moving the guiding blocks comprises moving along a guiding lane.

20. (Original) The method of claim 18, which further comprises moving the guiding blocks to a plurality of positions based on processing temperature.

21. (Previously presented) An apparatus for manufacturing semiconductor devices, comprising:

a susceptor on which a substrate is positioned comprising a plate, and a spacer disposed at the edge of the plate on which the edge of the substrate is laid, said spacer including a guiding lane along which the guiding blocks are moved;

a lift pin assembly for loading the substrate onto the susceptor;

a plurality of guiding blocks disposed around an edge of the susceptor, for positioning the substrate at an aligned position on the susceptor;

a guiding block transfer unit for moving the guiding blocks on the susceptor, wherein each of the guiding blocks moves along the guiding lane within a range defined by a radius of the plate;

a shaft rotatable by a driver in a predetermined range of distances;

a plurality of horizontally-extending supporting rods attached to the shaft;

a plurality of transfer rods connected between the supporting rods and the guiding blocks, the transfer rods being pivotally coupled to the supporting rods so that when the shaft rotates, the guiding blocks move along the guiding lanes and the transfer rods pivot, each of the transfer rods including:

- a horizontal portion pivotally coupled to the supporting rods;
- a vertical portion coupled to the horizontal portion; and
- a connection portion pivotally coupled to the vertical portion and the guiding

block.

22. (Cancelled)

23. (Previously presented) An apparatus for manufacturing semiconductor devices, comprising:

a susceptor for positioning a substrate thereon, the susceptor comprising a plate, and a spacer disposed at the edge of the plate on which the edge of the substrate is laid, said spacer including a guiding lane along which the guiding blocks are moved;

a lift pin assembly for loading the substrate onto the susceptor;

a plurality of guiding blocks disposed around an edge of the susceptor, for positioning the substrate at an aligned position on the susceptor; and

a guiding block transfer unit for moving the guiding blocks on the susceptor, wherein each of the guiding blocks moves horizontally along the guiding lane within a range defined by a radius of the plate, the guiding plate further comprising:

a shaft rotatable by a driver in a predetermined range of distances;

a plurality of horizontally-extending supporting rods, attached to the shaft;

a plurality of transfer rods connected between the supporting rods and the guiding blocks, the transfer rods being pivotally coupled to the supporting rods so that when the shaft rotates the guiding blocks move along the guiding lanes and the transfer rods pivot, each of the transfer rods including:

a horizontal portion pivotally coupled to the supporting rods;

a vertical portion coupled to the horizontal portion; and

a connection portion pivotally coupled to the vertical portion and the guiding block.